



92/IFW

500.39825X00

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): T. HIROSE, et al  
Serial No.: 09/800,495  
Filed: March 8, 2001  
For: METHOD OF DETECTING AND MEASURING ENDPOINT OF  
POLISHING PROCESSING AND ITS APPARATUS AND  
METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE  
USING THE SAME  
Group: 1765  
Examiner: L. Umez-Eronini

**STATEMENT OF SUBSTANCE OF INTERVIEW**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

October 20, 2004

Sir:

Applicants note that an Interview Summary accompanied the Notice of Allowance and confirm that the undersigned attorney conducted a telephone interview with the Examiner, L. Umez-Eronini, on September 20, 2004, during which time amendments to the claims 1 and 9 as effected by the Examiner's Amendment accompanying the Notice of Allowance and Interview Summary, were discussed and authorized in order to place the application in condition for allowance. Thus, applicants confirm the substance of the interview as provided by the Interview Summary and although applicants consider the submission of this paper to be unnecessary, to avoid any question concerning the requirements for applicant to file a statement of the substance of the interview, this statement is submitted.

Respectfully submitted,

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Registration No. 22,466  
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